Zibo Seno Electronic Engineering Co., Ltd.

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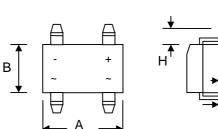


EMB1F – EMB6F 🚱 👬

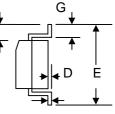
1.0A SUPER FAST SURFACE MOUNT GLASS PASSIVATED BRIDGE RECTIFIER

Features

- Glass Passivated Die Construction
- Low Forward Voltage Drop
- High Current Capability
- High Surge Current Capability
- Designed for Surface Mount Application
- Plastic Material UL Flammability 94V-O



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Dim

Α

В

С

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MB-F

Max

4.95

4.10

0.35

0.20

7.00

1.10

1.70

1.60

2.70

1.80

Min

4.50

3.60

0.15

6.40

0.50

1.30

1.20

2.30

All Dimensions in mm

Mechanical Data

- Case: MB-F, Molded Plastic
- Terminals: Plated Leads Solderable per MIL-STD-202, Method 208
- Polarity: As Marked on Case
- Weight: 0.134 grams (approx.)
- Mounting Position: Any
- Marking: Type Number
- Lead Free: For RoHS / Lead Free Version

Maximum Ratings and Electrical Characteristics @T_A=25°C unless otherwise specified

Single Phase, half wave, 60Hz, resistive or inductive load. For capacitive load, derate current by 20%.

Characteristic	Symbol	EMB1F	EMB2F	EMB4F	EMB6F	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	Vrrm Vrwm Vr	100	200	400	600	V
RMS Reverse Voltage	VR(RMS)	70	140	280	560	V
Average Rectified Output Current (Note 1) $@T_A = 40^{\circ}C$ Average Rectified Output Current (Note 2) $@T_A = 40^{\circ}C$		1.0				А
Non-Repetitive Peak Forward Surge Current 8.3ms Single half sine-wave superimposed on rated load (JEDEC Method)	IFSM	35				A
$I^{2}t$ Rating for Fusing (t < 8.3ms)	l ² t	5.0			A ² s	
Forward Voltage per element $@I_F = 1.0A$	Vfm	0.95 1.25		1.7	V	
Peak Reverse Current $@T_A = 25^{\circ}C$ At Rated DC Blocking Voltage $@T_A = 125^{\circ}C$	IDM	5.0 500				μA
Reverse Recovery Time (Note 4)	trr	35				nS
Typical Junction Capacitance per leg (Note 3)	Cj	13			pF	
Typical Thermal Resistance per leg (Note 1)	RθJA RθJL	62.5 25			°C/W	
Operating and Storage Temperature Range	Тj, Tsтg	-55 to +150				°C

Note: 1. Mounted on glass epoxy PC board with 1.3mm² solder pad.

2. Mounted on aluminum substrate PC board with 1.3mm² solder pad.

3. Measured at 1.0 MHz and applied reverse voltage of 4.0V D.C.

4. Measured with IF = 0.5A, IR = 1.0A, IRR = 0.25A. See figure 5.

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